Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
		* : Required Field	

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-27
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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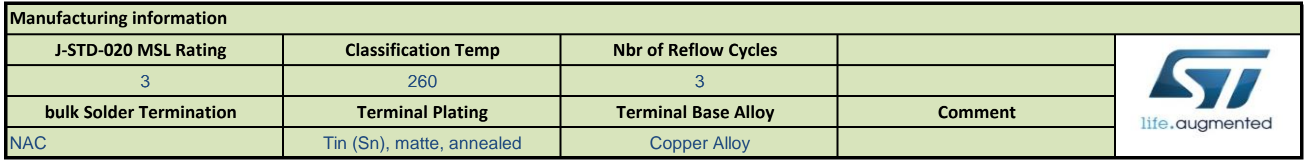
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9396	AA9I*UAJ6BBP	A	MU1A	2017-01-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	260.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.0	64	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th June 2014	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AA9I*UAJ6BBP					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or Dies	Other inorganic materials	10.891	mg	supplier	die	Silicon (Si)	7440-21-3		9.806	mg	900376	37715
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	2112	88
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.603	mg	55367	2319
Die or Dies				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	92	4
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	367	15
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.035	mg	3214	135
Die or Dies				supplier	metallization	Nickel (Ni)	7440-02-0		0.075	mg	6886	288
Die or Dies				supplier	metallization	Platinum (Pt)	7440-06-4		0.042	mg	3856	162
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.151	mg	13865	581
Die or Dies				supplier	glass coating	Glass: Silicon Dioxide (Si02)	7631-86-9		0.151	mg	13865	581
Leadframe	Copper & its alloys	28.890	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.508	mg	952163	105800
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.647	mg	22395	2488
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.039	mg	1350	150
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1177	131
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.606	mg	20976	2331
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.020	mg	692	77
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.018	mg	623	69
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.018	mg	623	69
Die attach		2.501	mg	supplier	glue or tape	Bismaleimide resin	Proprietary		0.075	mg	29988	288
Die attach				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.188	mg	75170	723
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		2.238	mg	894842	8608
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		1.179	mg	1000000	4535
encapsulation		216.418	mg	supplier	mold compound	Epoxy Resin	Proprietary		15.835	mg	73169	60904
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		15.835	mg	73169	60904
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		182.424	mg	842924	701631
encapsulation				supplier	mold compound	Quartz	14808-60-7		0.634	mg	2930	2438
encapsulation				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.056	mg	4879	4062
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.634	mg	2930	2438